

BONDING DEVICE, ULTRASONIC TRANSDUCER AND BONDING METHOD**Abstract**

The invention relates to a bonding device, particularly for producing bond
5 connections between electrical conductors made of wire material or strip material
and contact points of substrates such as, in particular, electrical circuits, wherein
the bonding device comprises a bonding head (2) which can be rotated about a
geometric axis of rotation (D), in particular a vertical axis, and on which a
bonding tool (5) and an ultrasonic transducer (35) are disposed for ultrasonic
10 vibration excitation of the bonding tool (5). In order to further develop a bonding
device of the abovementioned type, it is proposed that the main direction of
extension (36) of the ultrasonic transducer (35) and/or the direction of extension
thereof in the direction of the axis of the minimum moment of inertia extends
parallel to the geometric axis of rotation (D) of the bonding head (2). According
15 to further aspects, the invention further relates to a bonding device or an
ultrasonic transducer.

[Figure No. 3]